

S/N 10/823,314

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Neo C. Peng et al.

Examiner: Samuel M Heinrich

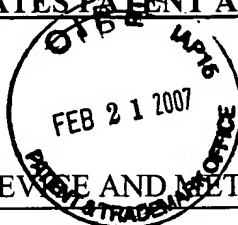
Serial No.: 10/823,314

Group Art Unit: 1725

Filed: April 13, 2004

Docket No.: 303.772US2

Title: WAFER DICING DEVICE AND METHOD



AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This paper responds to the Office Action mailed on December 5, 2006. Please amend the above-identified patent application as follows.

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02 FC:1201 800.00 DA